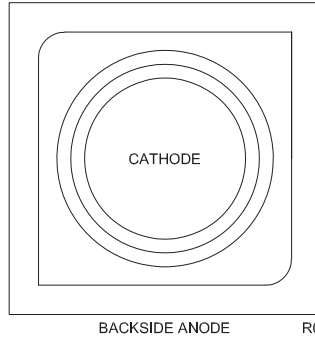


CPZ35R-CMATVS3V3

Uni-Directional TVS Die

3.3 Volt

The CPZ35R-CMATVS3V3 is a silicon uni-directional transient voltage suppressor designed for low leakage and fast response against ESD spikes.



MECHANICAL SPECIFICATIONS:

Die Size	10.2 x 10.2 MILS
Die Thickness	3.9 MILS
Cathode Bonding Pad Size	7.0 MILS DIAMETER
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 12,000Å
Scribe Alley Width	1.97 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	163,034

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Electrical Fast Transient (IEC 61000-4-4) (5x50ns)	EFT	40	A
ESD Voltage (IEC 61000-4-2, Air)	V _{ESD}	30	kV
ESD Voltage (IEC 61000-4-2, Contact)	V _{ESD}	30	kV
Operating and Storage Junction Temperature	T _J , T _{stg}	-55 to +150	°C

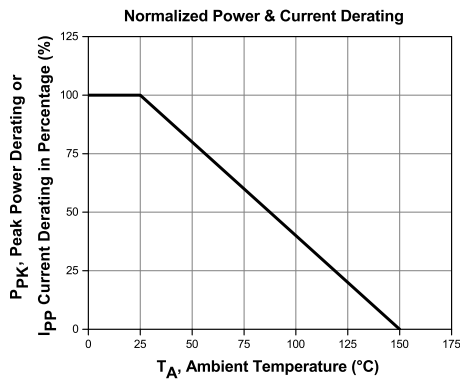
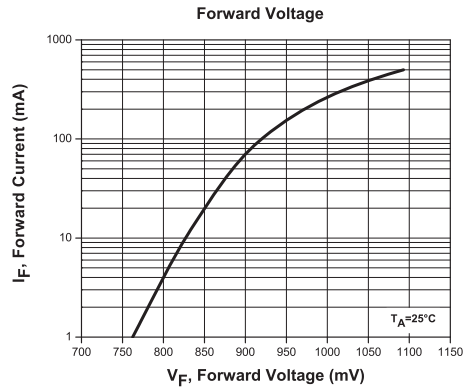
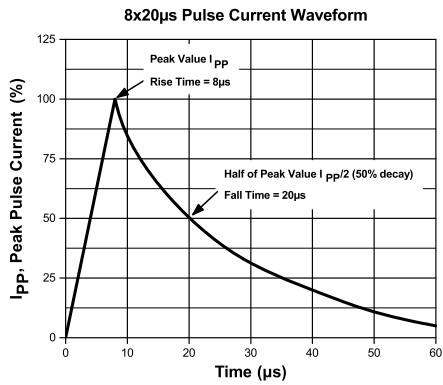
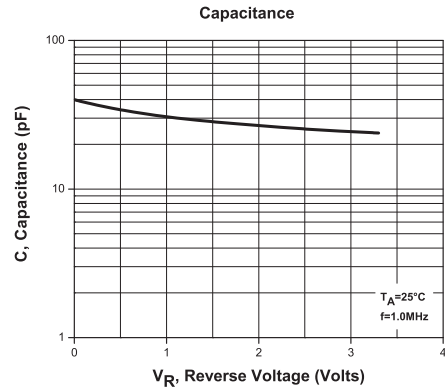
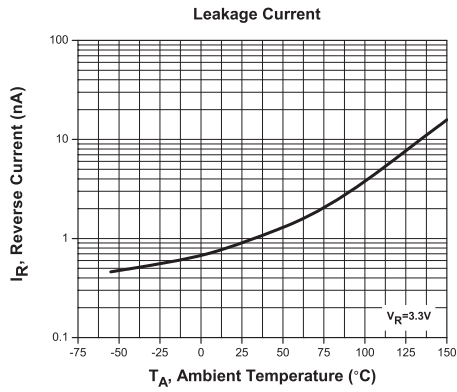
ELECTRICAL CHARACTERISTICS: (T_A=25°C) V_F=0.9V MAX @ I_F=10mA (for all types)

Maximum Reverse Stand-off Voltage V _{VRWM}	Minimum Breakdown Voltage		Maximum Reverse Leakage Current I _R @ V _{VRWM}	Maximum Clamping Voltage (8x20µs)		Typical TLP Clamping Voltage (Note 1)		Typical Dynamic Resistance (Note 1) R _{DYN}	Typical Junction Capacitance @ 0V Bias C _J
	V _{BR} @ I _T			V _C @ I _{PP}	A	V _{CL} @ I _{PP}	A		
V	V	mA	µA	V	A	V	A	Ω	pF
3.3	5.0	1.0	2.5	11	7.0	6.0	11.3	0.5	45
						3.0	5.3		

Note 1: Transmission Line Pulse (TLP) conditions: Z₀=50Ω, t_p=100ns

CPZ35R-CMATVS3V3

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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